

Operating Values

#	Name	Value	Category	Description
1.	Cin IRMS	306.023 mA	Capacitor	Input capacitor RMS ripple current
2.	Cin Pd	280.95 μ W	Capacitor	Input capacitor power dissipation
3.	Cout IRMS	136.283 mA	Capacitor	Output capacitor RMS ripple current
4.	Cout Pd	18.573 nW	Capacitor	Output capacitor power dissipation
5.	D1 Tj	38.074 degC	Diode	D1 junction temperature
6.	Diode Pd	57.673 mW	Diode	Diode power dissipation
7.	IC Ipk	1.236 A	IC	Peak switch current in IC
8.	IC Pd	515.89 mW	IC	IC power dissipation
9.	IC Tj	51.668 degC	IC	IC junction temperature
10.	IC Tolerance	18.0 mV	IC	IC Feedback Tolerance
11.	ICThetaJA	42.0 degC/W	IC	IC junction-to-ambient thermal resistance
12.	Iin Avg	920.02 mA	IC	Average input current
13.	L Ipp	472.1 mA	Inductor	Peak-to-peak inductor ripple current
14.	L Pd	275.01 mW	Inductor	Inductor power dissipation
15.	Cin Pd	280.95 μ W	Power	Input capacitor power dissipation
16.	Cout Pd	18.573 nW	Power	Output capacitor power dissipation
17.	Diode Pd	57.673 mW	Power	Diode power dissipation
18.	IC Pd	515.89 mW	Power	IC power dissipation
19.	L Pd	275.01 mW	Power	Inductor power dissipation
20.	Total Pd	850.54 mW	Power	Total Power Dissipation
21.	BOM Count	10	System	Total Design BOM count
22.	Cross Freq	103.835 kHz	Information	Bode plot crossover frequency
23.	Duty Cycle	89.541 %	Information	Duty cycle
24.	Efficiency	96.576 %	System	Steady state efficiency
25.	FootPrint	156.0 mm ²	Information	Total Foot Print Area of BOM components
26.	Frequency	541.105 kHz	System	Switching frequency
27.	Gain Marg	3.187 dB	Information	Bode Plot Gain Margin
28.	Iout	1.0 A	System	Iout operating point
29.	Low Freq Gain	53.793 dB	Information	Gain at 1Hz
30.	Mode	CCM	System	Conduction Mode
31.	Phase Marg	61.875 deg	Information	Bode Plot Phase Margin
32.	Pout	23.99 W	System	Total output power
33.	Total BOM	NA	Information	Total BOM Cost
34.	Vin	27.0 V	System	Vin operating point
35.	Vout	23.99 V	System	Operational Output Voltage
36.	Vout Actual	23.985 V	Information	Vout Actual calculated based on selected voltage divider resistors

#	Name	Value	Category	Description
37.	Vout Tolerance	4.404 %	System Information	Vout Tolerance based on IC Tolerance (no load) and voltage divider resistors if applicable
38.	Vout p-p	1.269 mV	System Information	Peak-to-peak output ripple voltage

Design Inputs

Name	Value	Description
Iout	1.0	Maximum Output Current
VinMax	27.0	Maximum input voltage
VinMin	25.0	Minimum input voltage
Vout	24.0	Output Voltage
base_pn	LV14360P	Base Product Number
source	DC	Input Source Type
Ta	30.0	Ambient temperature

WEBENCH® Assembly

Component Testing

Some published data on components in datasheets such as Capacitor ESR and Inductor DC resistance is based on conservative values that will guarantee that the components always exceed the specification. For design purposes it is usually better to work with typical values. Since this data is not always available it is a good practice to measure the Capacitance and ESR values of C_{in} and C_{out} , and the inductance and DC resistance of $L1$ before assembly of the board. Any large discrepancies in values should be electrically simulated in WEBENCH to check for instabilities and thermally simulated in WebTHERM to make sure critical temperatures are not exceeded.

Soldering Component to Board

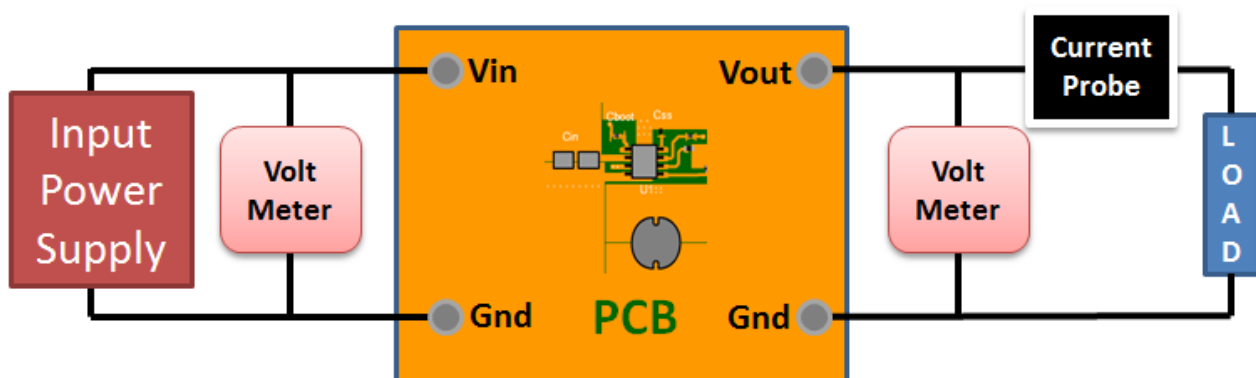
If board assembly is done in house it is best to tack down one terminal of a component on the board then solder the other terminal. For surface mount parts with large tabs, such as the DPAK, the tab on the back of the package should be pre-tinned with solder, then tacked into place by one of the pins. To solder the tab down to the board place the iron down on the board while resting against the tab, heating both surfaces simultaneously. Apply light pressure to the top of the plastic case until the solder flows around the part and the part is flush with the PCB. If the solder is not flowing around the board you may need a higher wattage iron (generally 25W to 30W is enough).

Initial Startup of Circuit

It is best to initially power up the board by setting the input supply voltage to the lowest operating input voltage 25.0V and set the input supply's current limit to zero. With the input supply off connect up the input supply to V_{in} and GND. Connect a digital volt meter and a load if needed to set the minimum load of the design from V_{out} and GND. Turn on the input supply and slowly turn up the current limit on the input supply. If the voltage starts to rise on the input supply continue increasing the input supply current limit while watching the output voltage. If the current increases on the input supply, but the voltage remains near zero, then there may be a short or a component misplaced on the board. Power down the board and visually inspect for solder bridges and recheck the diode and capacitor polarities. Once the power supply circuit is operational then more extensive testing may include full load testing, transient load and line tests to compare with simulation results.

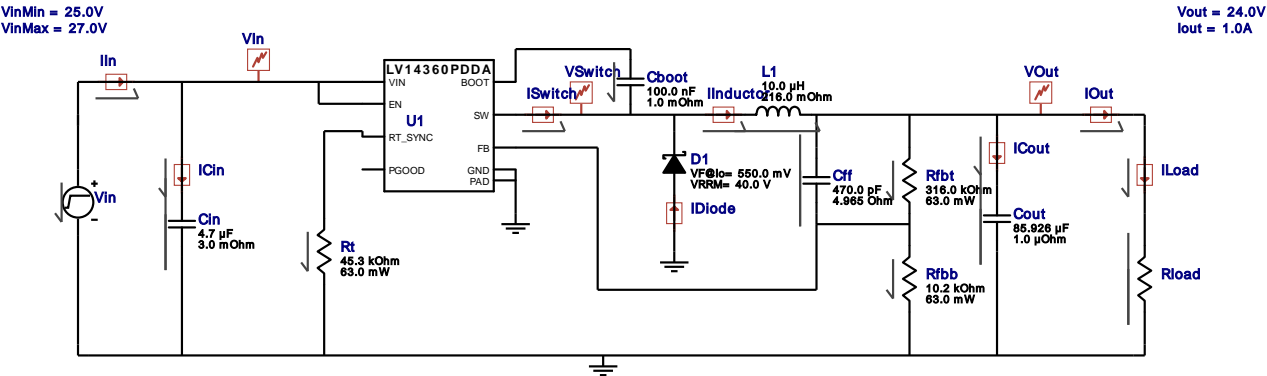
Load Testing

The setup is the same as the initial startup, except that an additional digital voltmeter is connected between V_{in} and GND, a load is connected between V_{out} and GND and a current meter is connected in series between V_{out} and the load. The load must be able to handle at least rated output power + 50% (7.5 watts for this design). Ideally the load is supplied in the form of a variable load test unit. It can also be done in the form of suitably large power resistors. When using an oscilloscope to measure waveforms on the prototype board, the ground leads of the oscilloscope probes should be as short as possible and the area of the loop formed by the ground lead should be kept to a minimum. This will help reduce ground lead inductance and eliminate EMI noise that is not actually present in the circuit.



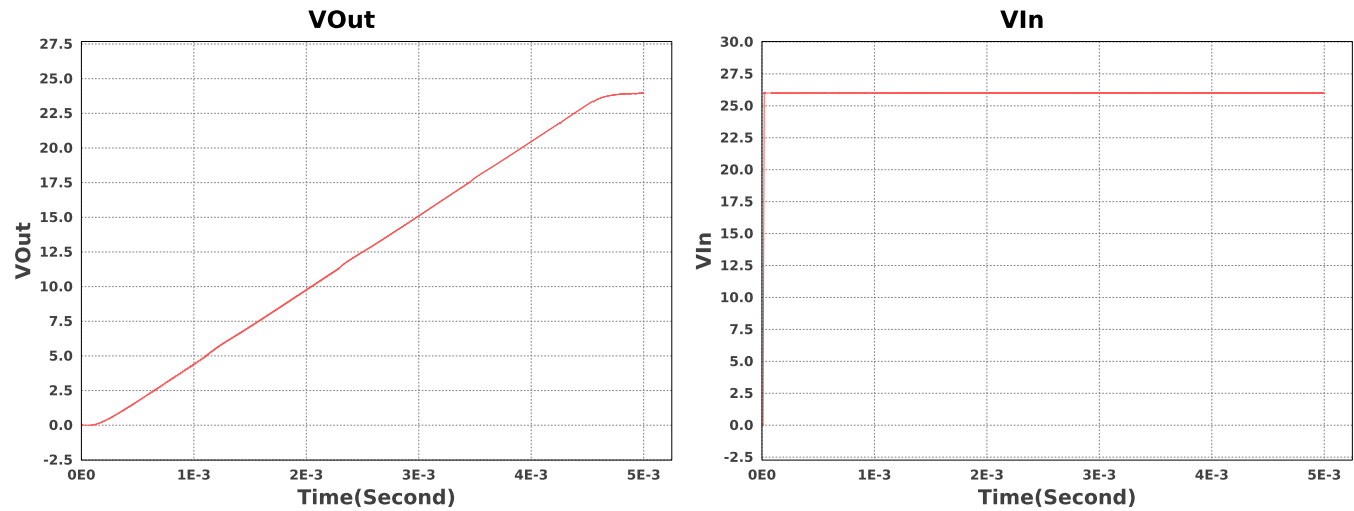
WEBENCH® Electrical Simulation Report

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sim_id = 1
Simulation Type = Startup

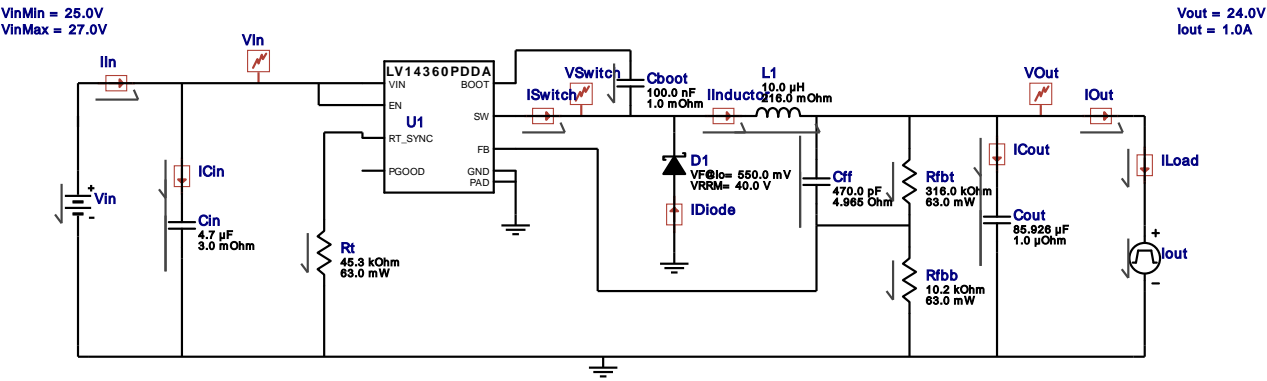


Simulation Parameters

#	Name	Parameter Name	Description	Values
1.	Rload	R	Load resistance	24.0 ohm

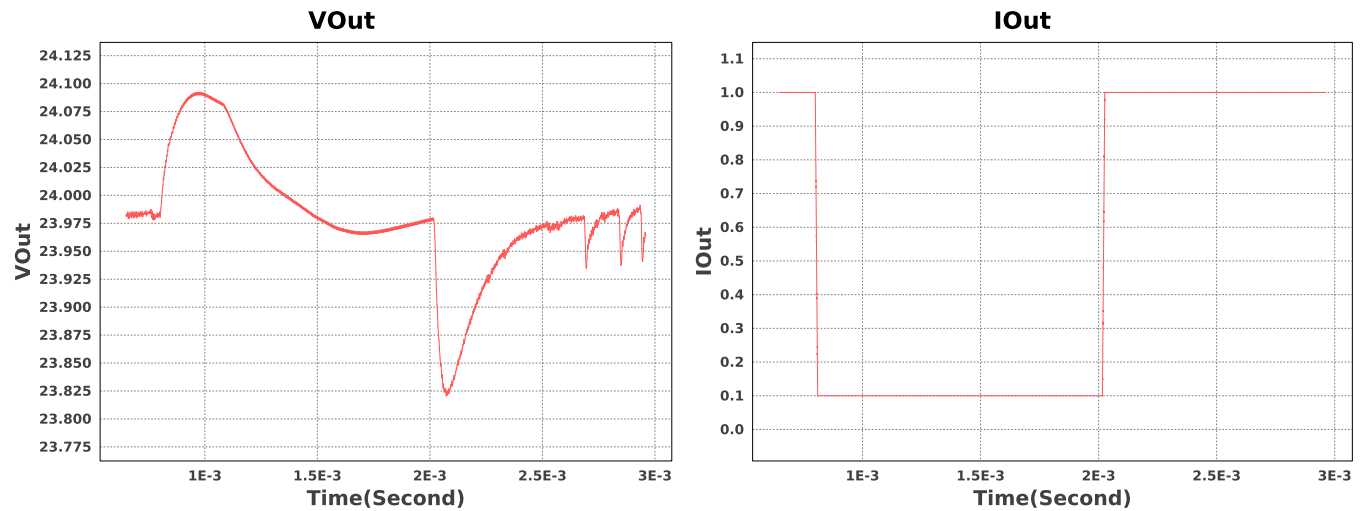


Design Id = 37
sim_id = 2
Simulation Type = Load Transient

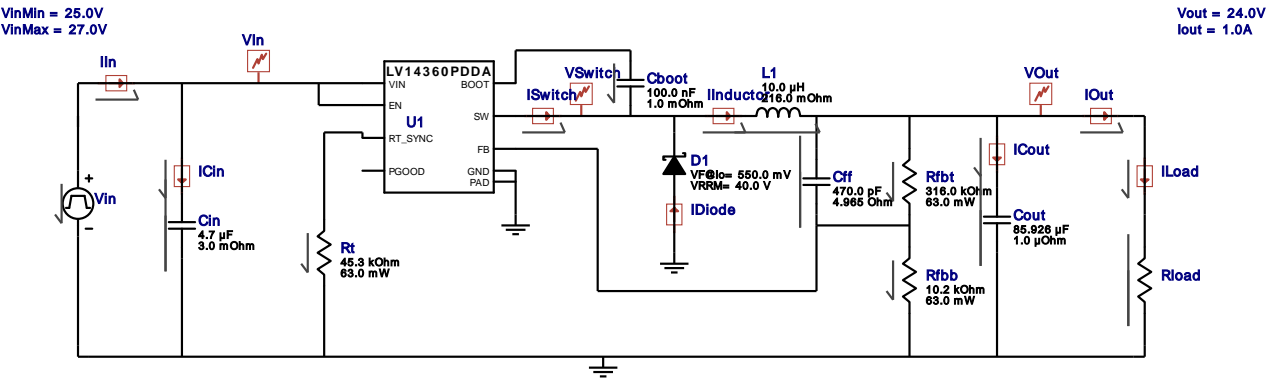


Simulation Parameters

#	Name	Parameter Name	Description	Values
1.	Cboot	IC	no description	5
2.	L1	IC	no description	-1.0
3.	Cout	IC	no description	24.0
4.	ILoad	I	Load current	Iload1 A
5.	Iout	Signal_type	Signal Type	PULSE
		I1	Initial input current	1.0 A
		I2	Peak Input current	0.1 A
		Td	Initial time delay	800u s
		Tr	Rise time	10u
		Tf	Fall time	10u s
		Pw	Pulse width	0.0012062313676038925 s

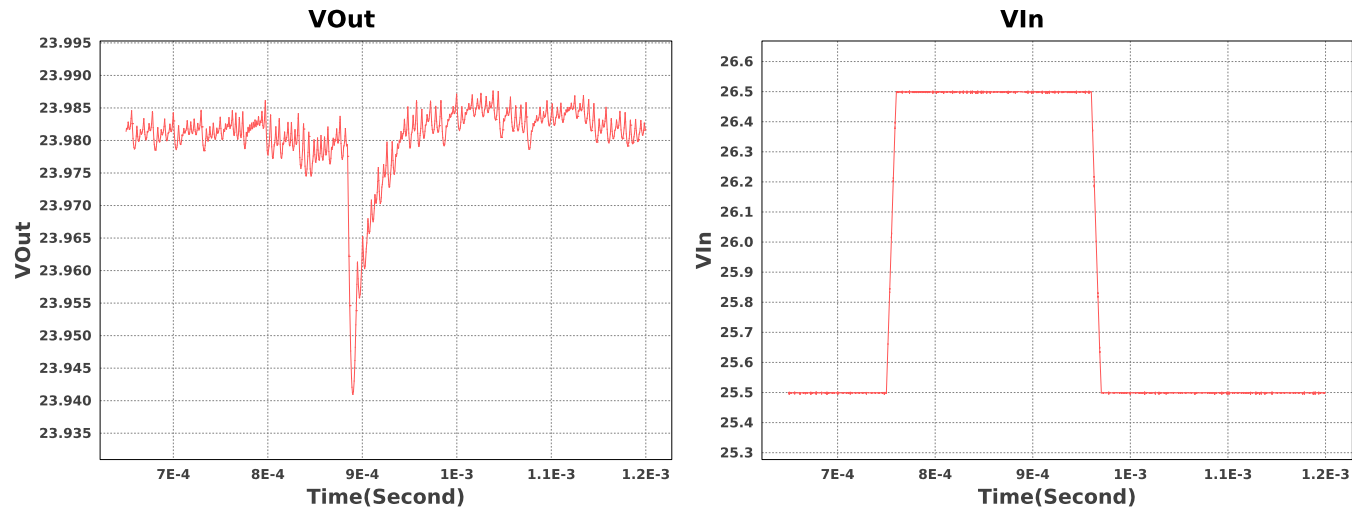


Design Id = 37
sim_id = 3
Simulation Type = Input Transient

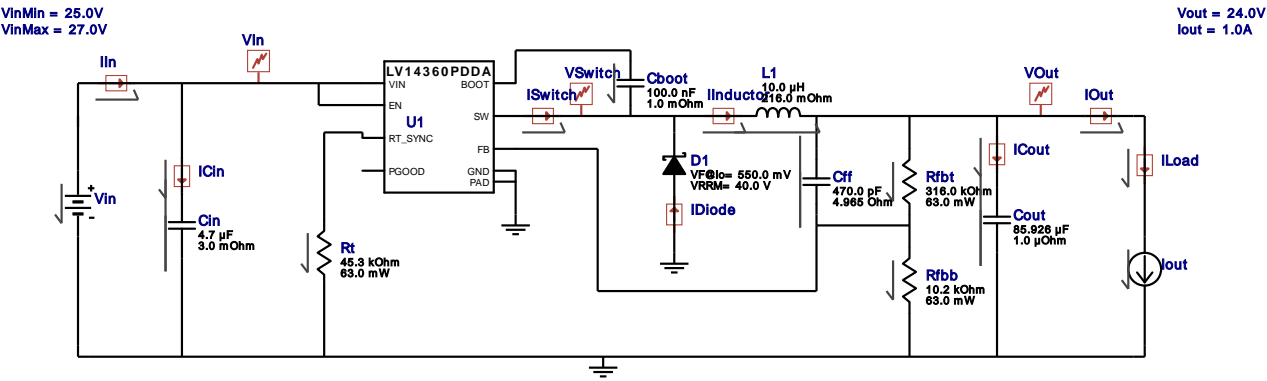


Simulation Parameters

#	Name	Parameter Name	Description	Values
1.	Cboot	IC	no description	5
2.	L1	IC	no description	-1.0
3.	Cout	IC	no description	24.0
4.	Rload	R	Load Resistance	24.0 ohm

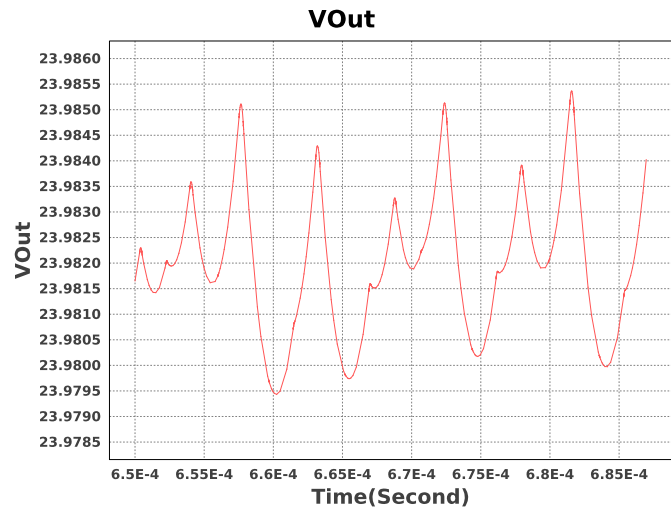


Design Id = 37
sim_id = 4
Simulation Type = Steady State



Simulation Parameters

#	Name	Parameter Name	Description	Values
1.	Cboot	IC	no description	5
2.	L1	IC	no description	-1.0
3.	Cout	IC	no description	24.0
4.	Iout	I	Load current	1.0 A



Design Assistance

- 1. Master key : A19BF6113C34B063[v1]
- 2. LV14360P Product Folder : <http://www.ti.com/product/LV14360> : contains the data sheet and other resources.

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